

(0.635 mm) .025"

MIS SERIES

# MIXED TECHNOLOGY SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts contact askjim@toby.co.uk

**Insulator Material:** Liquid Crystal Polymer  
**Contact Material:** Phosphor Bronze

**Plating:** Au or Sn over 50 μ" (1.27 μm) Ni  
**Operating Temp Range:** -55 °C to +125 °C

**Voltage Rating:** 275 VAC

**Max Cycles:** 100

**RoHS Compliant:** Yes

## PROCESSING

**Lead-Free Solderable:** Yes

**SMT Lead Coplanarity:** (0.10 mm) .004" max (019-057)

**Board Stacking:** For applications requiring more than two connectors per board contact askjim@toby.co.uk

## RECOGNITIONS

For complete scope of recognitions Contact askjim@toby.co.uk



FILE NO. E111594

## ALSO AVAILABLE (MOQ Required)

- 11 mm, 16 mm, 18.75 mm and 22 mm stack height
- 30 μ" (0.76 μm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row

Contact Samtec.

**Board Mates:** MIT

SO

**Standoffs:** SO

SO

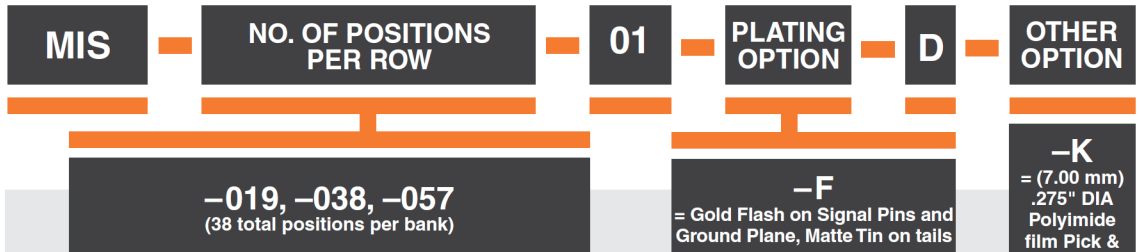
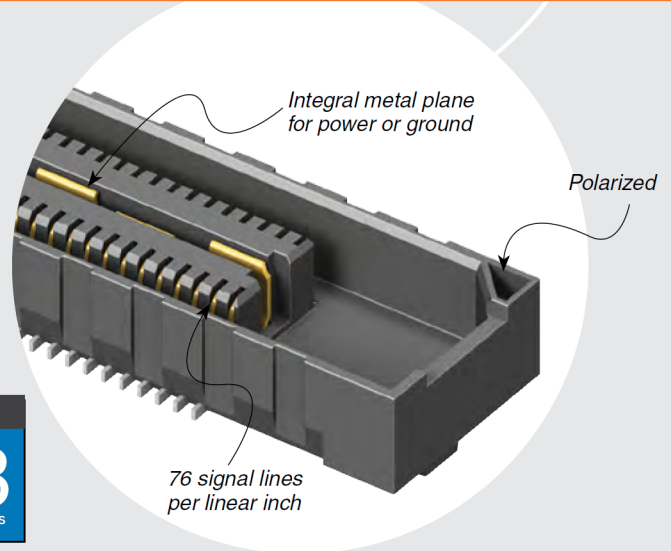


## HIGH-SPEED CHANNEL PERFORMANCE

MIT/MIS @ 5 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

**28**  
Gbps



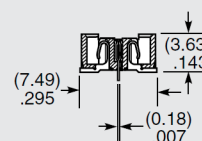
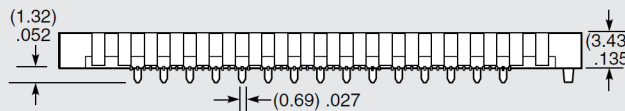
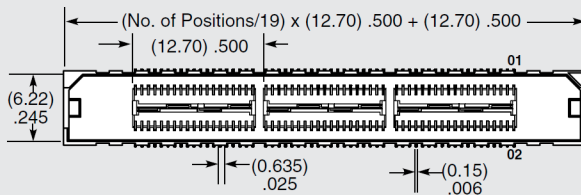
**-F**  
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

**-L**  
= 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

**-C\***  
= Electro-Polished Selective 50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, 10 μ" (0.25 μm) min Au over 50 μ" (1.27 μm) Ni on Ground Plane in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails

**-K**  
= (7.00 mm) .275" DIA Polyimide film Pick & Place Pad

**-TR**  
= Tape & Reel



\*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

Note: Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.

MATED HEIGHT*		
MIS LEAD STYLE	MIT LEAD STYLE	
	-01	-02
-01	(5.00) .197	(8.00) .315

\*Processing conditions will affect mated height. See SO Series for board space tolerances.